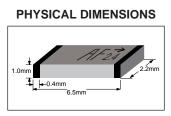


2.45GHz ULTRA COMPACT CHIP ANTENNA DATA GUIDE

DESCRIPTION

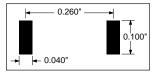
The exciting ANT-2.45-CHP is of the one of the world's smallest, high-performance 2.4 Ghz Chip Antennas. It is ideal for all 2.4GHz applications including Bluetooth, 802.11, home RF, ZigBee and other popular and emerging standards. The antenna uses an advanced multilayer LTCC Technology and a proprietary hybrid spiral element to achieve size and performance characteristics superior to other designs. The incredibly compact SMD package measures a mere 6.5mm (L) x 2.2mm (W) x 1.0mm (H) and is fully compatible with hand- and reflowattachment processes. The antenna's favorable electrical specifications, stability and costeffectiveness make it the logical choice for a wide variety of applications.



Actual Size



Pad Layout



FEATURES

- Incredibly Compact SMD Package
- Superior LTCC Technology
- 50Ω Characteristic Impedance
- Low Loss
- Wide Bandwidth
- Favorable Linear Polarization
- > Unity Gain

APPLICATIONS

Any 2.4GHz Wireless Product Including:

- Bluetooth
- 802.11
- ZigBee
- Wireless PCMCIA Cards
- Telemetry
- Data Collection
- Industrial Process Monitoring
- Compact Wireless Products
- External Antenna Elimination

No External Matching Required

- Highly Stable Over Temp. and Humidity
- Fully Hand- and Reflow-Assembly Compatible
- Cost-Effective

ORDERING	INFORMATION

	DESCRIPTION
ANT-2.45-CHP-x	2.45GHz Ultra-Compact
	Chip Antenna

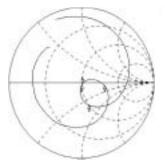
x= "T" for Tape/Reel, "B" for Bulk Standard Reel is 3,000 pcs. Quantities less than 3,000 pcs. supplied in Bulk.

PHYSICAL SPECIFICATIONS		
Dimensions	6.5 x 2.2 x 1.0	
Operating Temperature	-25~85°C	
Construction	LTCC	

ELECTRICAL PERFORMANCE		
Polarization	Linear	
Operating Frequency	2,400~2,488	
Center Frequency	2,450 MHz	
Bandwidth	180.0 MHz	
Maximum Gain	0.8dBi	
Impedance	50Ω	

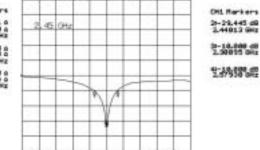
CHARACTERISTICS

Impedance

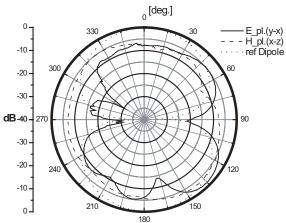


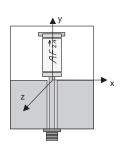


Return Loss



Radiation Pattern





SOLDERING CONSIDERATIONS

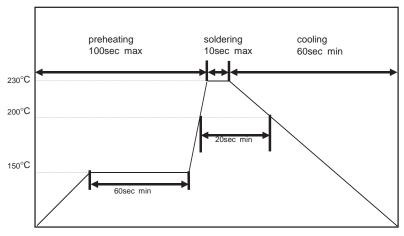
Hand Soldering

This antenna is designed for high-volume automated assembly, however, it may be successfully attached by hand assembly techniques. A hand-solder temperature of 225° or lower should be used. Do not exceed a 10 sec. heating time.

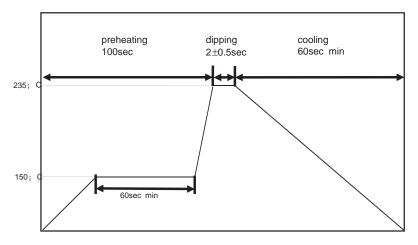
Reflow Temperature Profile

The single most critical stage in the automated assembly process is the reflow process. The reflow profile below should be closely followed since excessive temperatures or transport times during reflow will irreparably damage the antennas. Assembly personnel will need to pay careful attention to the oven's profile to insure that it meets the requirements necessary to successfully reflow all components while still meeting the limits mandated by the antennas themselves.

REFLOW SOLDERING PROFILE



FLOW SOLDERING PROFILE





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